

- **Members of the Texas Instruments Widebus™ Family**
- **EPIC™ (Enhanced-Performance Implanted CMOS) Process**
- **Operating Range 2-V to 5.5-V  $V_{CC}$**
- **Distributed  $V_{CC}$  and GND Pins Minimize High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015**
- **Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

### description

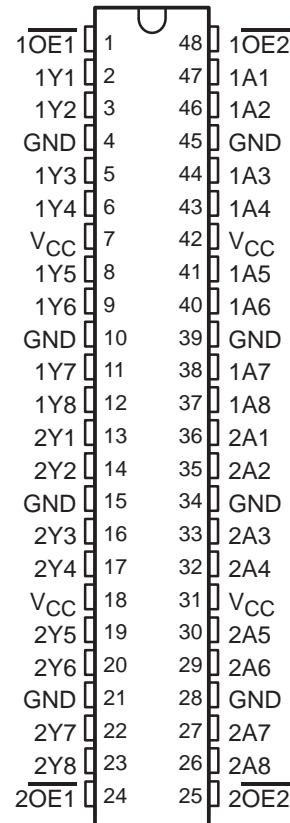
These 16-bit buffers and bus drivers provide a high-performance bus interface for wide data paths.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable ( $\overline{OE}_1$  or  $\overline{OE}_2$ ) input is high, all corresponding outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AHC16540 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74AHC16540 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

SN54AHC16540 . . . WD PACKAGE  
SN74AHC16540 . . . DGG, DGV, OR DL PACKAGE  
(TOP VIEW)



FUNCTION TABLE  
(each 8-bit buffer/driver)

INPUTS			OUTPUT
$\overline{OE}_1$	$\overline{OE}_2$	A	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z



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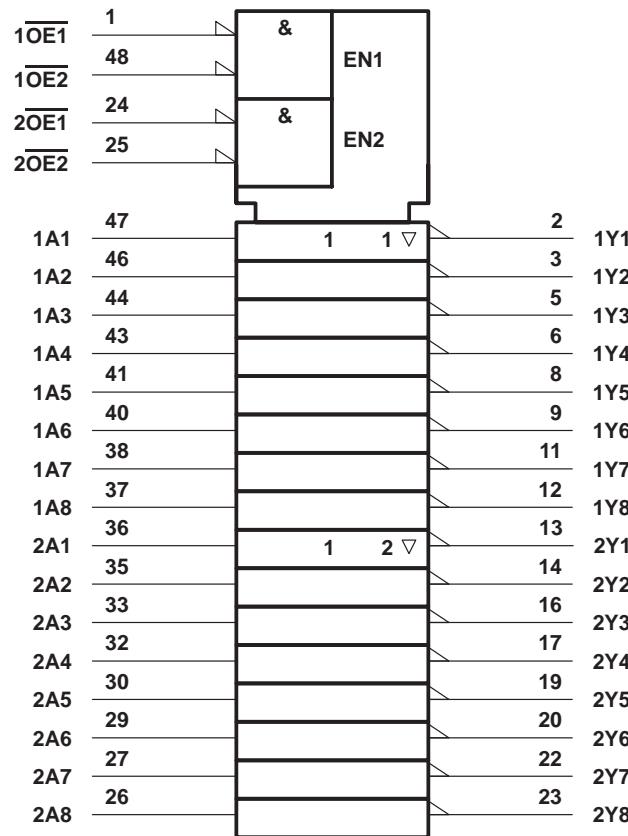


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**SN54AHC16540, SN74AHC16540  
16-BIT BUFFERS/DRIVERS  
WITH 3-STATE OUTPUTS**

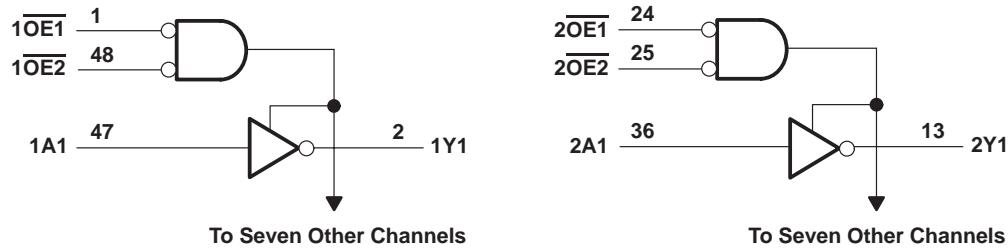
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**logic symbol†**



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		SN54AHC16540		SN74AHC16540		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	2	5.5	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	1.5	1.5	V
		V <sub>CC</sub> = 3 V	2.1	2.1	2.1	
		V <sub>CC</sub> = 5.5 V	3.85	3.85	3.85	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5	0.5	0.5	V
		V <sub>CC</sub> = 3 V	0.9	0.9	0.9	
		V <sub>CC</sub> = 5.5 V	1.65	1.65	1.65	
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V	-50	-50	-50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	-4	-4	-4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V	-8	-8	-8	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V	50	50	50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V	4	4	4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V	8	8	8	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V	100	100	100	ns/V
		V <sub>CC</sub> = 5 V ± 0.5 V	20	20	20	
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**SN54AHC16540, SN74AHC16540  
16-BIT BUFFERS/DRIVERS  
WITH 3-STATE OUTPUTS**

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54AHC16540		SN74AHC16540		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 µA	2 V	1.9	2		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		2.48		
		4.5 V	3.94			3.8		3.8		
	I <sub>OL</sub> = -8 mA									
V <sub>OL</sub>	I <sub>OL</sub> = 50 µA	2 V		0.1		0.1		0.1		V
		3 V		0.1		0.1		0.1		
		4.5 V		0.1		0.1		0.1		
	I <sub>OL</sub> = 4 mA	3 V		0.36		0.5		0.44		
		4.5 V		0.36		0.5		0.44		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	0 V to 5.5 V		±0.1		±1*		±1	µA	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND, V <sub>I</sub> (OE) = V <sub>IL</sub> or V <sub>IH</sub>	5.5 V		±0.25		±2.5		±2.5	µA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		4		40		40	µA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		2	10			10	pF	
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V		3					pF	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

**switching characteristics over recommended operating free-air temperature range,  
V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN54AHC16540		SN74AHC16540		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 15 pF	4.8**	8.4**		1**	10**	1	10	ns
t <sub>PHL</sub>				4.8**	8.4**		1**	10**	1	10	
t <sub>PZH</sub>	OE	Y	C <sub>L</sub> = 15 pF	6.8**	10.6**		1**	12.5**	1	12.5	ns
t <sub>PZL</sub>				6.8**	10.6**		1**	12.5**	1	12.5	
t <sub>PHZ</sub>	OE	Y	C <sub>L</sub> = 15 pF	6.8**	11.5**		1**	12.5**	1	12.5	ns
t <sub>PLZ</sub>				6.8**	11.5**		1**	12.5**	1	12.5	
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 50 pF	7.7	11		1	12.5	1	12.5	ns
t <sub>PHL</sub>				7.3	11		1	12.5	1	12.5	
t <sub>PZH</sub>	OE	Y	C <sub>L</sub> = 50 pF	9.7	14.1		1	16	1	16	ns
t <sub>PZL</sub>				7.1	14.1		1	16	1	16	
t <sub>PHZ</sub>	OE	Y	C <sub>L</sub> = 50 pF	9.4	14		1	16	1	16	ns
t <sub>PLZ</sub>				9.7	14		1	16	1	16	
t <sub>sk(o)</sub>			C <sub>L</sub> = 50 pF		1.5***				1.5	ns	

\*\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.

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switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	TA = 25°C			SN54AHC16540		SN74AHC16540		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 15 pF	3.7*	6*	1*	7*	1	7	ns	
t <sub>PHL</sub>				3.7*	6*	1*	7*	1	7		
t <sub>PZH</sub>	OE	Y	C <sub>L</sub> = 15 pF	4.7*	7.3*	1*	8.5*	1	8.5	ns	
t <sub>PZL</sub>				4.7*	7.3*	1*	8.5*	1	8.5		
t <sub>PHZ</sub>	OE	Y	C <sub>L</sub> = 15 pF	4.5*	7.2*	1*	8.5*	1	8.5	ns	
t <sub>PLZ</sub>				4.5*	7.2*	1*	8.5*	1	8.5		
t <sub>PLH</sub>	A	Y	C <sub>L</sub> = 50 pF	5.2	8	1	9	1	8.5	ns	
t <sub>PHL</sub>				5.2	8	1	9	1	8.5		
t <sub>PZH</sub>	OE	Y	C <sub>L</sub> = 50 pF	6.2	9.3	1	10.5	1	10.5	ns	
t <sub>PZL</sub>				6.2	9.3	1	10.5	1	10.5		
t <sub>PHZ</sub>	OE	Y	C <sub>L</sub> = 50 pF	6	9.2	1	10.5	1	10.5	ns	
t <sub>PLZ</sub>				6	9.2	1	10.5	1	10.5		
t <sub>sk(o)</sub>			C <sub>L</sub> = 50 pF	1**					1	ns	

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics,  $V_{CC} = 5 \text{ V}$ ,  $C_L = 50 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 4)

PARAMETER	SN74AHC16540			UNIT
	MIN	TYP	MAX	
V <sub>OL(P)</sub> Quiet output, maximum dynamic V <sub>OL</sub>		0.6		V
V <sub>OL(V)</sub> Quiet output, minimum dynamic V <sub>OL</sub>		-0.3		V
V <sub>OH(V)</sub> Quiet output, minimum dynamic V <sub>OH</sub>		4.7		V
V <sub>IH(D)</sub> High-level dynamic input voltage		3.5		V
V <sub>IL(D)</sub> Low-level dynamic input voltage		1.5		V

NOTE 4: Characteristics are for surface-mount packages only.

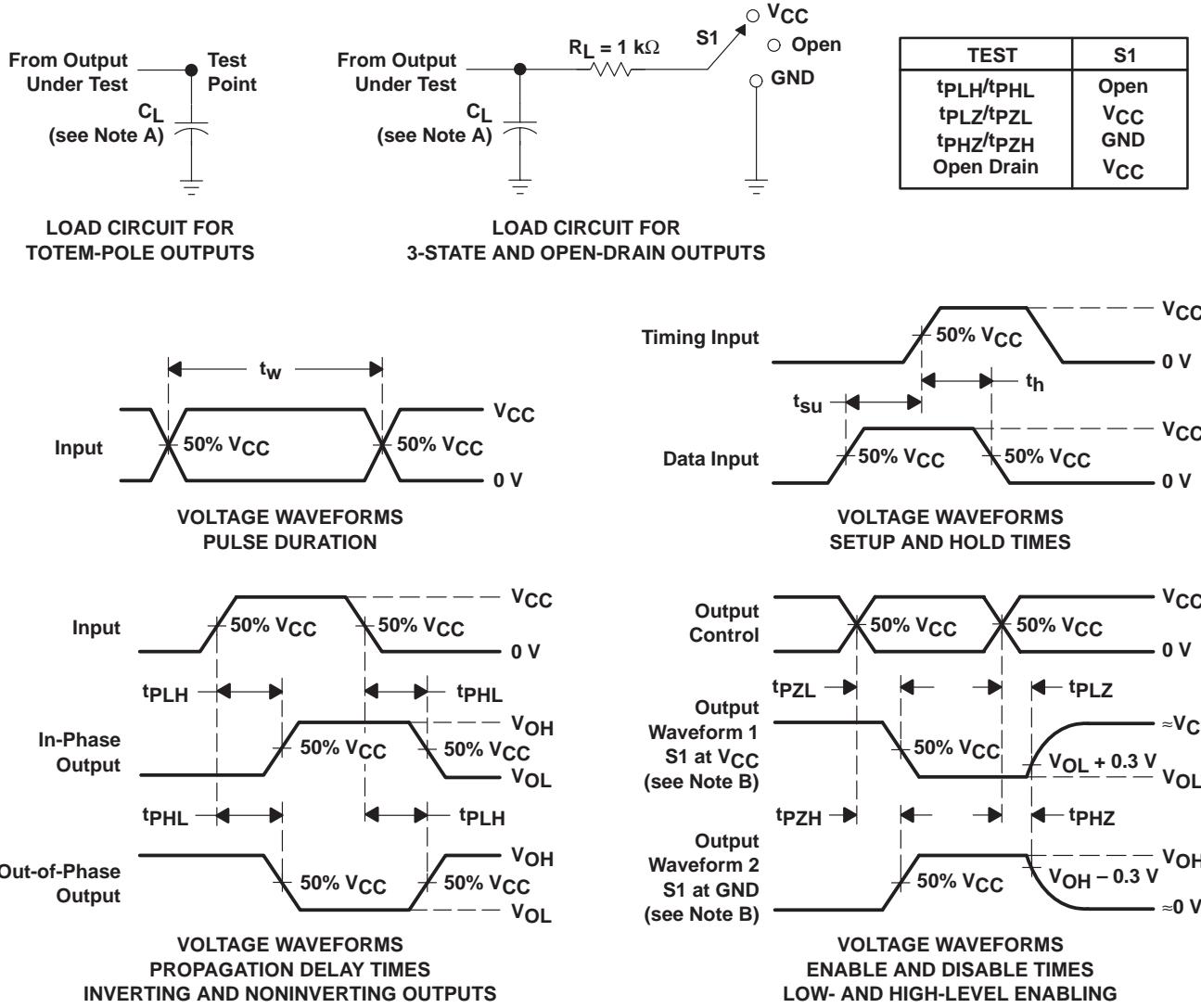
operating characteristics,  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load, f = 1 MHz	13	pF

**SN54AHC16540, SN74AHC16540  
16-BIT BUFFERS/DRIVERS  
WITH 3-STATE OUTPUTS**

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**PARAMETER MEASUREMENT INFORMATION**



NOTES:

- $C_L$  includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.
- The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AHC16540DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16540DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16540DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AHC16540DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16540DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16540DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16540DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHC16540DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

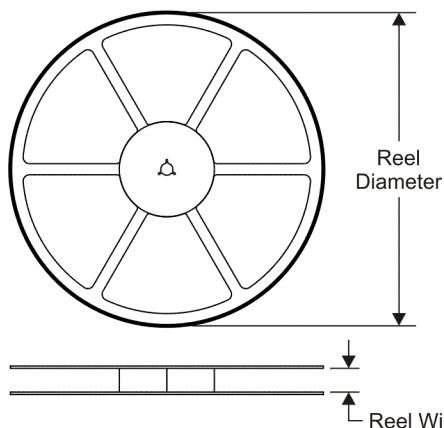
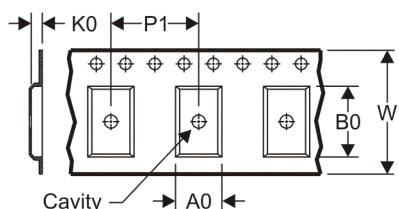
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

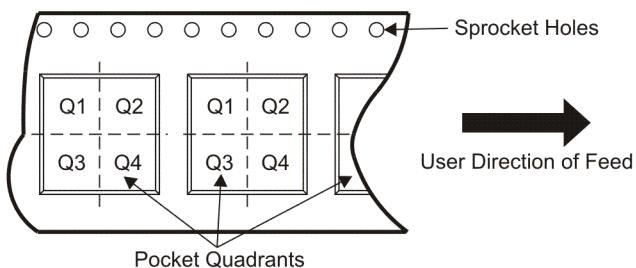
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC16540DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74AHC16540DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

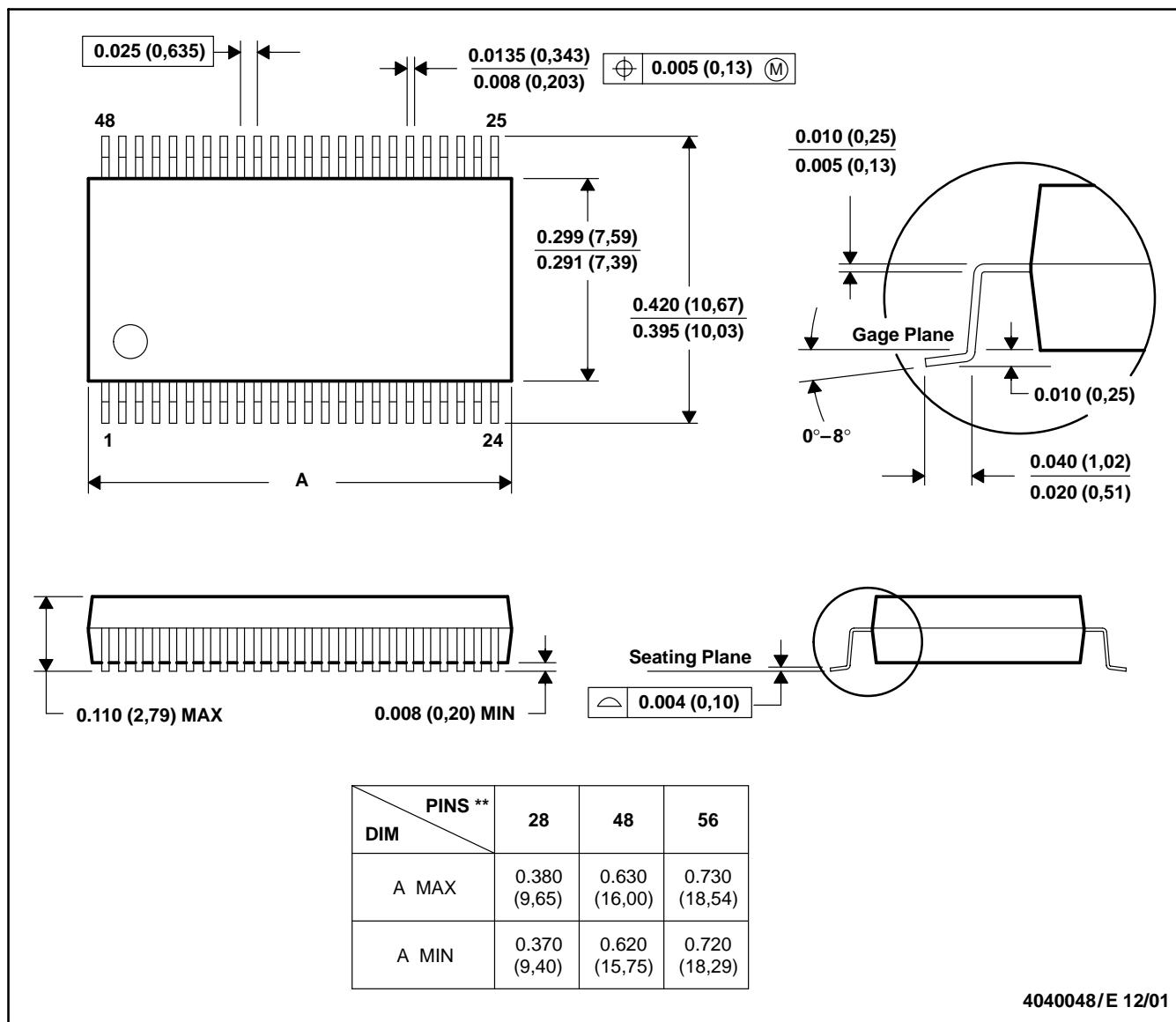

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC16540DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74AHC16540DGVR	TVSOP	DGV	48	2000	346.0	346.0	33.0

## DL (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

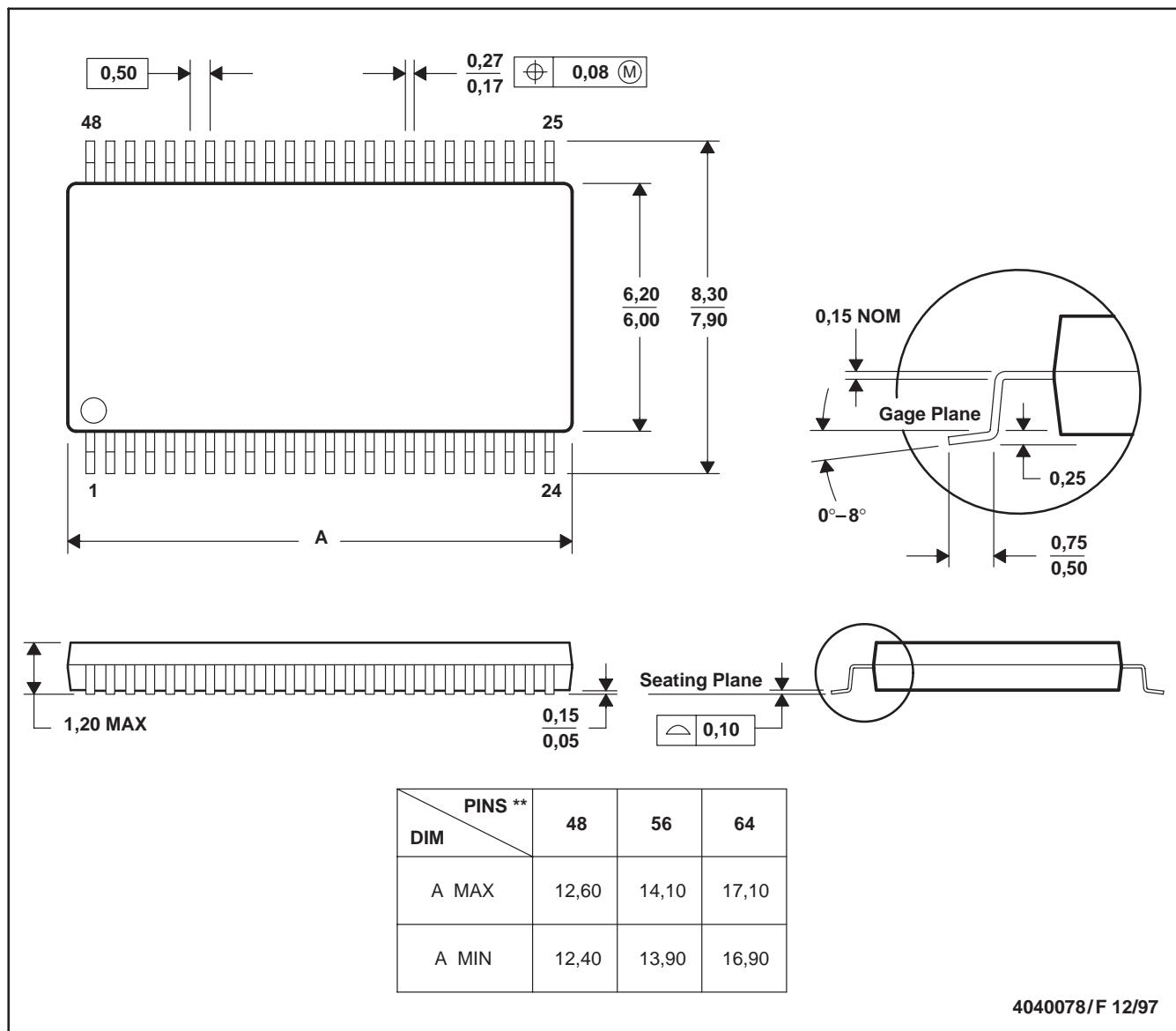


NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-118

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

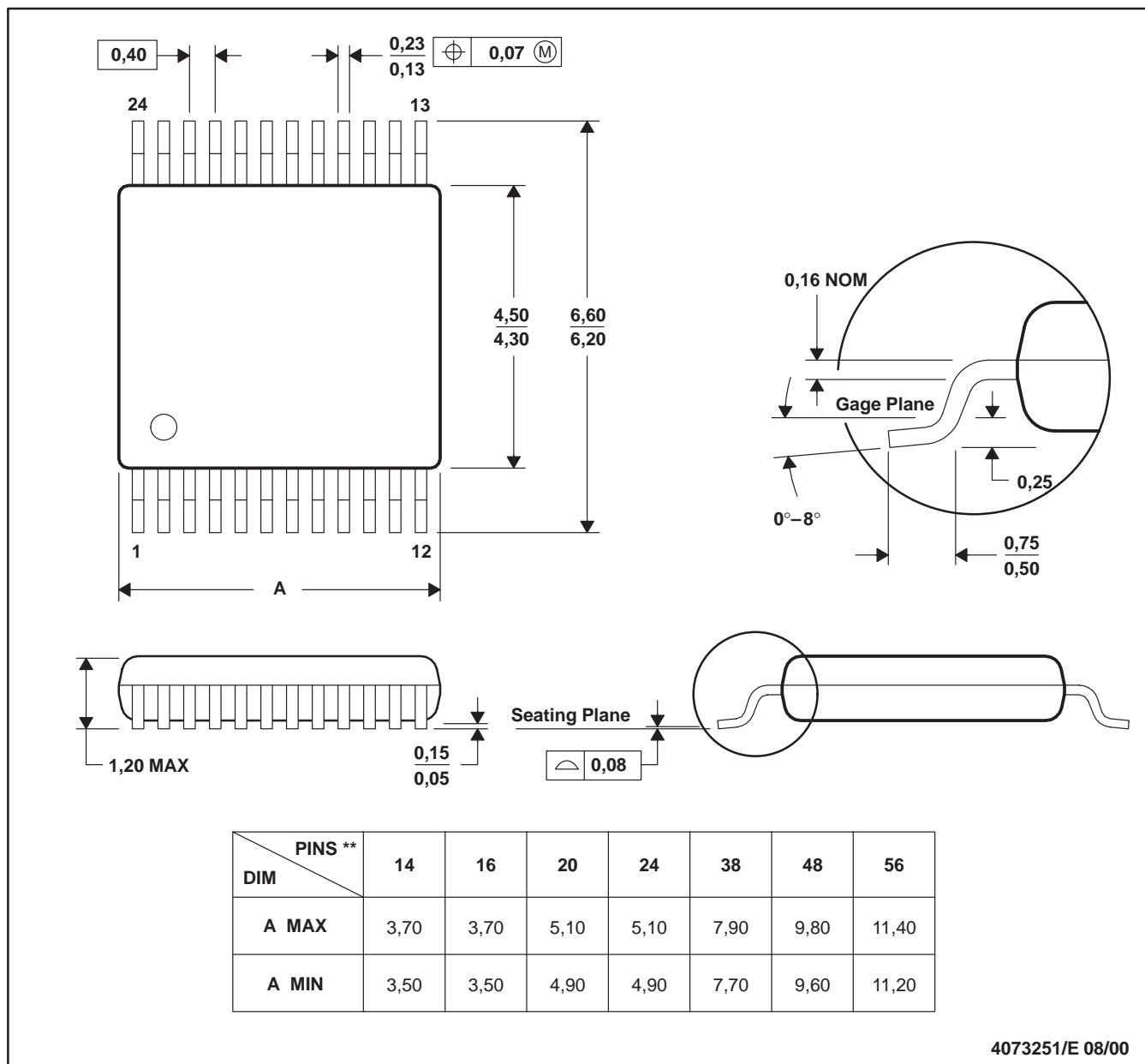


NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

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